

*Aug 21  
#2 and  
8-10-98  
J. Mandel*  
PATENT 7000-105  
TESSERA 3.3-018 CONT CONT II CONT 105

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of  
Khandros et al.

Group Art Unit:

Serial No.: Unassigned

Examiner:

Filed: On Even Date Herewith

Date: July 6, 1998

For: Face-Up Semiconductor  
Chip Assembly

X

Assistant Commissioner For Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Sir or Madame:

Preliminary to the initiation of the prosecution of the above-identified pending U.S. patent application, the following amendments and remarks are respectfully submitted.

**In the Title:**

Please amend the title of the application to: --Face-up  
Semiconductor Chip Assembly --.

**In the Specification:**

Please insert before the first line, after the title, the following:

**CROSS-REFERENCE TO RELATED APPLICATIONS**

*Amend.*  
This is a continuation of United States Patent Application No. 08/861,280, filed on May 21, 1997 which is in turn a continuation of United States Patent Application No. 08/319,966, filed on October 7, 1994, now United States Patent No. 5,685,885. United States Patent Application No. 08/319,966 is a

**EXPRESS MAIL LABEL NUMBER: EM411073384US**